

B. Amendments to the Specification

1. Please replace the paragraph on page 1, lines 6-8 with the following:

This application is a continuation of United States Patent Application No. 09/737,408, filed December 15, 2000, now United States Patent No. 6,613,605, which claims the benefit of Provisional Application Number 60/170,976 filed December 15, 1999, and also of Provisional Application Number 60/170,975 filed December 15, 1999, all of which are hereby incorporated by reference.

2. Please replace the paragraph on page 2, lines 4-8 with the following:

The present invention is an improved method of connecting to electronic devices by means of metal protuberances protruding from a supporting substrate. The improvement comprises forming the metal protuberances by depositing a metal on areas of the substrate that contain metallic sites; melting the metal into the shape of convex protuberances, and bonding the protuberances to said device.

3. Kindly replace the paragraph on page 5, lines 8-13 with the following:

One aspect of the invention comprises a method of forming connections for semi-conductors, electronic and electromechanical devices. The connecting means is an insulating substrate or base that has a conductive pattern. The conductive pattern forms the connection from the device to a package or a higher level assembly. The devices or semiconductor die or dice are joined to the conductive pattern by metal bumps or protuberances from the conductive pattern.

4. Please replace the paragraph on beginning on page 5, line 17, and ending on page 6, line 4, with the following paragraph:

The embodiment in FIG. 1, shows a compact, ceramic, chip carrier or single chip module (SCM), **100** with high packaging efficiency. The SCM has a conductive pattern on a ceramic substrate **110**. The substrate has area array contacts **120** for interconnection to second level packaging and a metal or ceramic ring frame **150** around the semiconductor device or integrated circuit chip. The area array of contacts may be an irregular array or a regular array such as a ball, pin, pad or column array. Preferably the area array consists of convex metal bumps melted onto the contact pads of the ceramic substrate as described in the copending application entitled HIGH DENSITY ELECTRONIC INTERCONNECTION, Serial No. 09/737,407, filed simultaneously with the current application. A metal or ceramic cover **170** is bonded to the frame to seal the module.

5. Please replace the paragraph on page 6, lines 13-15 with the following:

The frame of the module **150** fits closely around the integrated circuit die. For hermetically sealed modules, the frame is made of ceramic or metal and the frames are bonded to the substrate. A ceramic frame will preferably be metallized on its upper surface **160** for brazing to a metal cover.